

## IN THE CLAIMS

Please cancel original claims 1 through 10 contained in the English translation without prejudice.

Please insert new claims 11 through 30 as rewritten below.

-- 11. (New) Optoelectronic device having a first printed-circuit element, on which is mounted an optic emitter and/or receiver, having openings to receive centering pins of a complementary optic connector to be mounted facing said optic emitter and/or receiver, said optoelectronic device being provided further with a heatsink, wherein said first printed-circuit element is applied against a first face of said heatsink, and wherein a flexible printed-circuit segment connects a first element of said first printed circuit element to a second printed-circuit element, this second printed-circuit element being applied against a second face of the heatsink, this second face being separate from the first face.

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12. (New) Optoelectronic device according to claim 11, wherein said openings comprise holes located on said first printed circuit element.

13. (New) Device according to claim 11, wherein said first face is a secant relative to the second face, and in that said flexible printed-circuit segment forms an elbow.

14. (New) Device according to claim 13, wherein said elbow forms an angle of approximately 90 degrees.

15. (New) Device according to claim 11, wherein said first face and said second face are part of two planes intersecting each other, and in that said flexible printed-circuit segment forms an elbow linking said first and second printed circuit elements.

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16. (New) Device according to claim 11, wherein at least one of said first and second printed-circuit elements is rigid.

17. (New) Device according to claim 11, wherein at least one of said first and second printed-circuit elements is flexible and forms a single printed circuit with said printed-circuit flexible segment.

18. (New) Device according to claim 11, wherein the heatsink has two receptacles on its first face, these receptacles being at least a part of said openings and providing holding of the centering pins.

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19. (New) Device according to claim 11, wherein said optic receiver is positioned between said openings.

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20. (New) Device according to claim 12, wherein said optic receiver is positioned between said holes.

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21. (New) Device according to claim 11, wherein said second printed-circuit element has microbeads for connection with another device such as a motherboard.

22. (New) Device according to claim 21, wherein said second printed-circuit element has contact areas receiving contact studs of an intermediate connector coupling said second element of said printed circuit to an electronic board.

23. (New) Optoelectronic device according to claim 21, wherein said openings to receive said centering pins

comprise holes located on said first printed circuit element.

24. (New) Device according to claim 21, wherein said first face and said second face are part of two planes intersecting each other, and in that said flexible printed-circuit segment forms an elbow linking said first and second printed circuit elements.

25. (New) Device according to claim 21, wherein at least one of the first and second printed-circuit elements is rigid.

26. (New) Device according to claim 21, wherein at least one of the first and second printed-circuit elements is flexible and forms a single printed circuit with the printed-circuit flexible segment.

27. (New) Device according to claim 21, wherein the heatsink has two receptacles on its first face, these receptacles being positioned facing said openings and providing holding of the centering pins.

28. (New) Device according to claim 21, wherein said optic receiver is positioned between said openings.

29. (New) Device according to claim 21, wherein said second printed-circuit element has microbeads for connection with another device such as a motherboard.

30. (New) Device according to claim 21, wherein said intermediate connector is made up of two elements interconnectable by complementary coupling terminations

on an interconnection face, at least the element in contact with the second printed-circuit element being provided with solder microbeads on its face for connection with the second printed-circuit element.--

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